

Technology Innovation Forum

Wednesday, 26 April 2017 | 10:00 – 15:30hrs

SPICE Arena (Conference Room 4 & 5, Level 2), Penang, Malaysia

Organised by: 

Supporting Partner: 

Sponsored by:  

 **GLOBALFOUNDRIES[®]** 

Theme: Industrial Internet of Things: Unlocking the Potential by Semiconductor Companies

Abstract: Industrial Internet of Things (IIoT) is poised to usher in a fundamental transformation in the man-machine interaction. It promises to bring about a significant transformation in manufacturing and other industrial sectors of the economy. It offers a tremendous economic potential and impact.

The unlocking of which also brings up various important questions like: How does this impact the existing industries, business models, value chains, work forces? What are the challenges? And where are the opportunities - the real value points for us in the semiconductor industry?

Join us at the SEMICON Technology Innovation Forum 2017 to get ideas and insights into how various key players are positioning themselves to unlock the potential of IIoT. Get access to some amazing speakers, insightful content and exclusive networking.

Target Audience:

- Industry leaders with stake in the semiconductor ecosystem
- Analysts
- Startups, Venture Capitalists

Theme for Panel Discussion: Industrial Internet of Things: Opportunities and Challenges for Semiconductor Companies



Session Chair:

Ms. Meenu SARIN

Director, VLSI Consultancy, Singapore

Time	Presentation
10:00-10:15	Welcome Remarks by Session Chair
10:15-10:45	Transforming 200mm Fabs Through Automation <i>Mr. YAP Ah Choi, Manager, Automation Engineering, GLOBALFOUNDRIES Singapore Pte Ltd, Singapore</i>
10:45-11:15	A Highly Integrated and Comprehensive SiP Solutions for IoT <i>Mr. Teck LEE, Senior Technical Manager, Corporate R&D, ASE Group, Taiwan</i>
11:15-11:30	Break & Networking Time
11:30-12:00	Implementing IIoT using SEMI Standards – A Platform Based Approach <i>Mr. Ranjan CHATTERJEE, Vice President, Emerging Business & Technology Office, Cimetrix, USA</i>
12:00-12:30	Opportunities and Challenges in End-to-End IoT Deployment <i>Dr. Thomas OOI, Solution Enabling Manager, Intel , Malaysia</i>
12:30-13:30	Conference Lunch
13:30-14:00	Enhancing Capital Efficiency and Fab Productivity for IoT Applications <i>Dr. David HAYNES, Senior Director, Business Development, IoT Solutions in the MEMS and Advanced Packaging business group, Lam Research Corporation, USA</i>
14:00-14:30	Enabling IoT Era, through Packaging Technology Innovations <i>Mr. Sivakumar MOHANDASS, Senior Director, Sales, Amkor Technology, Singapore</i>
14:30-15:15	Panel Discussion: Industrial Internet of Things: Opportunities and Challenges for Semiconductor Companies Moderator: <i>Ms. Meenu SARIN, Director, VLSI Consultancy, Singapore</i> Panelists: <ul style="list-style-type: none"> • <i>Mr. Sivakumar MOHANDASS, Senior Director, Sales, Amkor Technology , Singapore</i> • <i>Mr. Teck LEE, Senior Technical Manager, Corporate R&D, ASE Group, Taiwan</i> • <i>Mr. Ranjan CHATTERJEE, Vice President, Emerging Business & Technology Office, Cimetrix, USA</i> • <i>Mr. YAP Ah Choi, Manager, Automation Engineering, GLOBALFOUNDRIES Singapore Pte Ltd, Singapore</i> • <i>Dr. Thomas OOI, Solution Enabling Manager , Intel , Malaysia</i> • <i>Dr. David HAYNES, Senior Director, Business Development, IoT Solutions in the MEMS and Advanced Packaging business group, Lam Research Corporation, USA</i> • <i>Mr. Ayo KAJOPAIYE, Project Coordinator, Collaborative Technology Platforms, SEMI (HQ), USA</i>
15:15-15:30	Closing Remarks by Session Chair